



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

CONNECTOR SERIES:

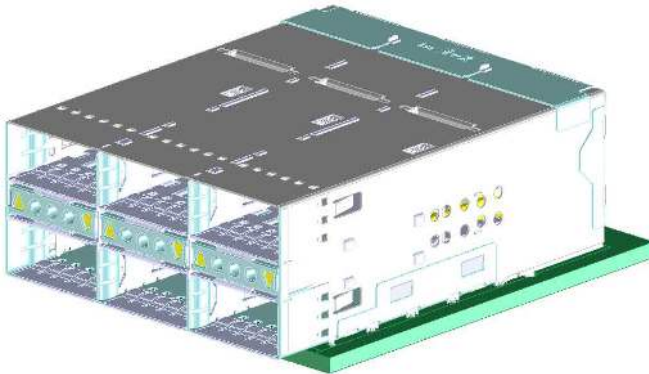
76871

76870 (STANDARD)

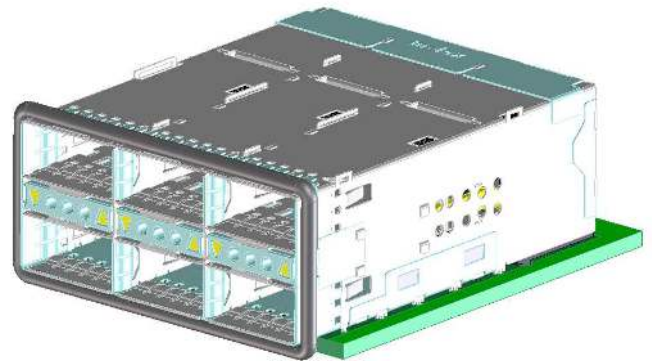
76894 (LOW-PROFILE)



76871 SERIES



76894 SERIES



76870 SERIES

TABLE OF CONTENTS

REVISION: D	ECR/ECN INFORMATION: EC No: UCP2012-2334 DATE: 2012 / 01 / 25	TITLE: PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	SHEET No. 1 of 17
DOCUMENT NUMBER: PS-76870-001	CREATED / REVISED BY: S. BOGIEL/JGONZALEZ	CHECKED BY: HAVERY	APPROVED BY: M. BANAKIS



PRODUCT SPECIFICATION

QSFP+ STACKED CONNECTORS

1.0	SCOPE	3
2.0	PRODUCT DESCRIPTION	3
2.1	PRODUCT NAME AND SERIES NUMBER(S).....	3
2.2	DIMENSION, MATERIALS, PLATING AND MARKINGS.....	3
2.3	SAFETY AGENCY APPROVALS.....	3
2.4	PIN ASSIGNMENTS.....	3
2.5	ADDITIONAL GENERAL SPECIFICATIONS.....	3
3.0	APPLICABLE DOCUMENTS AND SPECIFICATIONS	3
3.1	MOLEX DOCUMENTS.....	3
3.2	INDUSTRY DOCUMENTS.....	4
4.0	QUALIFICATION	4
5.0	RATINGS	4
5.1	VOLTAGE.....	4
5.2	CURRENT.....	4
5.3	TEMPERATURE.....	4
5.4	DURABILITY.....	4
6.0	PERFORMANCE (MECHANICAL & ENVIRONMENTAL)	5
6.1	TEST GROUP 1.....	5
6.2	TEST GROUP 2.....	6
6.3	TEST GROUP 3.....	7
6.4	TEST GROUP 4.....	8
	TEST GROUP 4 (CONTINUED).....	9
6.5	TEST GROUP 7.....	10
6.6	MECHANICAL TEST GROUP 1.....	11
6.7	MECHANICAL TEST GROUP 2.....	11
6.8	MECHANICAL TEST GROUP 3.....	12
6.9	MECHANICAL TEST GROUP 4.....	12
6.10	MECHANICAL TEST GROUP 5.....	13
6.11	MECHANICAL TEST GROUP 6.....	13
7.0	PACKAGING	14
8.1	CONNECTOR.....	14
8.2	PLUG AND CABLE ASSEMBLY.....	14
8.0	GAGES AND FIXTURES	15
9.0	OTHER INFORMATION	16
10.1	INVERTED SMT APPLICATION.....	16
10.2	PCB REQUIREMENTS.....	16

<u>REVISION:</u>	<u>ECR/ECN INFORMATION:</u>	<u>TITLE:</u>		<u>SHEET No.</u>
D	EC No: UCP2012-2334 DATE: 2012 / 01 / 25	PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS		2 of 17
<u>DOCUMENT NUMBER:</u>		<u>CREATED / REVISED BY:</u>	<u>CHECKED BY:</u>	<u>APPROVED BY:</u>
PS-76870-001		S. BOGIEL/JGONZALEZ	HAVERY	M. BANAKIS



PRODUCT SPECIFICATION

QSFP+ STACKED CONNECTORS

1.0 SCOPE

This Product Specification covers the QSFP – Stacked 2X1,2X3 Connector Series

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER(S)

Product Name: QSFP - Stacked Connector Family
 Connector Series: 76870, 76871, 76894

2.2 DIMENSION, MATERIALS, PLATING AND MARKINGS

See the appropriate sales drawing for information on dimensions, materials, plating, marking, and footprint patterns.

2.3 SAFETY AGENCY APPROVALS

UL file: E29179

2.4 PIN ASSIGNMENTS

Refer to appropriate sales drawing of the specific part number for the correct pin assignment.

2.5 ADDITIONAL GENERAL SPECIFICATIONS

MATERIALS:

- Cage: Nickel Silver - Unplated
- EMI Springs: Phos-Bronze – Nickel plated
- Air-Vents/EMI Shields: Die-cast Alloy – Nickel plated
- Light-pipes (if used): Polycarbonate
- Signal-Connector Housing: Thermoplastic, 94V-0
- Signal Terminals: Copper Alloy - Hard Gold plated over Nickel

2.6 MATING CONNECTORS

Plug & Cable Series: 74547, 74763, 111048

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

3.1 MOLEX DOCUMENTS

AS-76870-001 Application Specification
 PK-76870-001 Packaging Specification
 PS-45499-002 Cosmetic Specification

<u>REVISION:</u> D	<u>ECR/ECN INFORMATION:</u> EC No: UCP2012-2334 DATE: 2012 / 01 / 25	<u>TITLE:</u> PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	<u>SHEET No.</u> 3 of 17
<u>DOCUMENT NUMBER:</u> PS-76870-001	<u>CREATED / REVISED BY:</u> S. BOGIEL/JGONZALEZ	<u>CHECKED BY:</u> HAVERY	<u>APPROVED BY:</u> M. BANAKIS



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

3.2 INDUSTRY DOCUMENTS

EIA 364 Series	Electrical Connector Test Procedures Including Environmental Classifications with Test Procedures
EIA 364-1000	Environmental Test Methodology for Assessing the Performance of Connectors and Sockets Used in Business Office Applications

4.0 QUALIFICATION

Laboratory condition and sample selection are in accordance with EIA 364

5.0 RATINGS

5.1 VOLTAGE

30 Volts AC (RMS)/DC Max.

5.2 CURRENT

0.5 Amps Max.

5.3 TEMPERATURE

Operating:	-40°C to +85°C
Non-operating:	-55°C to +105°C

5.4 DURABILITY

PL2 #15 – Performance Level 1 – 0.76 µm Au – 250 cycles, 10 year Life (FMG)

<u>REVISION:</u> D	<u>ECR/ECN INFORMATION:</u> EC No: UCP2012-2334 DATE: 2012 / 01 / 25	<u>TITLE:</u> PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	<u>SHEET No.</u> 4 of 17
<u>DOCUMENT NUMBER:</u> PS-76870-001	<u>CREATED / REVISED BY:</u> S. BOGIEL/JGONZALEZ	<u>CHECKED BY:</u> HAVERY	<u>APPROVED BY:</u> M. BANAKIS



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

6.0 PERFORMANCE (MECHANICAL & ENVIRONMENTAL)

6.1 TEST GROUP 1

ITEM	TEST	TEST PROCEDURE	CONDITION	REQUIREMENT	ACTUAL
1	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	baseline	N/A
2	Durability (precondition)	EIA-364-09; perform plug & unplug cycles: 20		No evidence of physical damage	PASS
3	Temperature Life	EIA-364-17, method A, Test Condition 3 at 105°±2°C: 120 hours	Mated	None	
4	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	<10 mΩ Δ max	<10 mΩ Δ max
5	Reseating	Manually unplug & plug the connector, 3 cycles		No evidence of physical damage	PASS
6	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	<10 mΩ Δ max	<10 mΩ Δ max

<u>REVISION:</u> D	<u>ECR/ECN INFORMATION:</u> EC No: UCP2012-2334 DATE: 2012 / 01 / 25	<u>TITLE:</u> PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	<u>SHEET No.</u> 5 of 17
<u>DOCUMENT NUMBER:</u> PS-76870-001	<u>CREATED / REVISED BY:</u> S. BOGIEL/JGONZALEZ	<u>CHECKED BY:</u> HAVERY	<u>APPROVED BY:</u> M. BANAKIS



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

6.2 TEST GROUP 2

ITEM	TEST	TEST PROCEDURE	CONDITION	REQUIREMENT	ACTUAL
1	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	baseline	N/A
2	Durability (precondition)	EIA-364-09; perform plug & unplug cycles: 20		No evidence of physical damage	PASS
3	Thermal Shock	EIA-364-32, test condition I (10 cycles): 120 hours	Mated	None	
4	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	<10 mΩ Δ max	<10 mΩ Δ max
5	Cyclic Temperature & Humidity	EIA-364-31 Cycle connectors between 25° ± 3°C at 80% RH and 65 °± 3 °C at 50% RH (24 cycles) Ramp times should be 0.5 hour and dwell should be 1.0 hour.	Mated	None	
6	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	<10 mΩ Δ max	<10 mΩ Δ max
7	Reseating	Manually unplug & plug the connector, 3 cycles		No evidence of physical damage	PASS
8	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	<10 mΩ Δ max	<10 mΩ Δ max

REVISION: D	ECR/ECN INFORMATION: EC No: UCP2012-2334 DATE: 2012 / 01 / 25	TITLE: PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	SHEET No. 6 of 17
DOCUMENT NUMBER: PS-76870-001	CREATED / REVISED BY: S. BOGIEL/JGONZALEZ	CHECKED BY: HAVERY	APPROVED BY: M. BANAKIS



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

6.3 TEST GROUP 3

ITEM	TEST	TEST PROCEDURE	CONDITION	REQUIREMENT	ACTUAL
1	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	baseline	N/A
2	Durability (precondition)	EIA-364-09; perform plug & unplug cycles: 20		No evidence of physical damage	PASS
3	Temperature Life (precondition)	EIA-364-17, method A, Test Condition 3 at 105°±2°C 72 hours	Mated	None	
4	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	<10 mΩ Δ max	<10 mΩ Δ max
5	Mechanical Vibration	EIA-364-28 test condition VII test condition letter D 15 minutes in each of 3 mutually perpendicular directions. Both mating halves rigidly fixed to not contribute to relative motion of one contact against another.	Mated	Discontinuity < 1 μsec No evidence of physical damage	PASS
7	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	<10 mΩ Δ max	<10 mΩ Δ max

REVISION: D	ECR/ECN INFORMATION: EC No: UCP2012-2334 DATE: 2012 / 01 / 25	TITLE: PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	SHEET No. 7 of 17
DOCUMENT NUMBER: PS-76870-001	CREATED / REVISED BY: S. BOGIEL/JGONZALEZ	CHECKED BY: HAVERY	APPROVED BY: M. BANAKIS



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

6.4 TEST GROUP 4

ITEM	TEST	TEST PROCEDURE	CONDITION	REQUIREMENT	ACTUAL
1	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	baseline	N/A
2	Durability (precondition)	EIA-364-09; perform plug & unplug cycles: 20		No evidence of physical damage	PASS
3	Temperature Life (precondition)	EIA-364-17, method A, Test Condition 3 at 105°±2°C 72 hours	Mated	None	
4	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	<10 mΩ Δ max	<10 mΩ Δ max
5	Mixed Flowing Gas	EIA-364-35 class IIA, Option 1A & 1B test condition VII 14 days	See Note	None	
6	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	<10 mΩ Δ max	<10 mΩ Δ max

Note:

1. Expose ½ of the specimens unmated for 2/3 of the test duration. Mate the specimen to the same one used during preconditioning temperature life. Expose for the duration of the test.
2. Characterize porosity & plating thickness before test sequence.

REVISION: D	ECR/ECN INFORMATION: EC No: UCP2012-2334 DATE: 2012 / 01 / 25	TITLE: PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	SHEET No. 8 of 17
DOCUMENT NUMBER: PS-76870-001	CREATED / REVISED BY: S. BOGIEL/JGONZALEZ	CHECKED BY: HAVERY	APPROVED BY: M. BANAKIS



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

TEST GROUP 4 (CONTINUED)

ITEM	TEST	TEST PROCEDURE	CONDITION	REQUIREMENT	ACTUAL
7	Thermal Disturbance	Cycle connectors 10 times between 15° ± 3°C at 80% RH and 85 °± 3 °C at 50% RH. Ramps should be a minimum of 2°C per minute and dwell times should insure that the contacts reach the temperature extremes for a minimum of 5 minutes.	Mated	None	
8	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA .	Mated	<10 mΩ Δ max	<10 mΩ Δ max
9	Reseating	Manually unplug & plug the connector, 3 cycles		No evidence of physical damage	PASS
10	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA .	Mated	<10 mΩ Δ max	<10 mΩ Δ max

<u>REVISION:</u> D	<u>ECR/ECN INFORMATION:</u> EC No: UCP2012-2334 DATE: 2012 / 01 / 25	<u>TITLE:</u> PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	<u>SHEET No.</u> 9 of 17
<u>DOCUMENT NUMBER:</u> PS-76870-001	<u>CREATED / REVISED BY:</u> S. BOGIEL/JGONZALEZ	<u>CHECKED BY:</u> HAVERY	<u>APPROVED BY:</u> M. BANAKIS



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

6.5 TEST GROUP 7

ITEM	TEST	TEST PROCEDURE	CONDITION	REQUIREMENT	ACTUAL
1	Dielectric Withstanding Voltage	EIA-364-20; apply a voltage of 300 VDC for 1 minute between adjacent terminals and between adjacent terminals and ground.	Mated	No disruptive discharge No leakage current in excess of 5mA	PASS
2	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	baseline	N/A
3	Durability	EIA-364-09; perform plug & unplug cycles: 250		No evidence of physical damage	PASS
4	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	<10 mΩ Δ max	<10 mΩ Δ max
5	Dielectric Withstanding Voltage	EIA-364-20; apply a voltage of 300 VDC for 1 minute between adjacent terminals and between adjacent terminals and ground.	Mated	No disruptive discharge No leakage current in excess of 5mA	PASS

Note:

1. Separate sets of test specimens will be used to access dielectric withstanding voltage and the change in low level contact resistance.
2. Dielectric withstanding voltage testing will use different contacts than those used for low level contact resistance testing.

<u>REVISION:</u> D	<u>ECR/ECN INFORMATION:</u> EC No: UCP2012-2334 DATE: 2012 / 01 / 25	<u>TITLE:</u> PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	<u>SHEET No.</u> 10 of 17
<u>DOCUMENT NUMBER:</u> PS-76870-001	<u>CREATED / REVISED BY:</u> S. BOGIEL/JGONZALEZ	<u>CHECKED BY:</u> HAVERY	<u>APPROVED BY:</u> M. BANAKIS



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

6.6 MECHANICAL TEST GROUP 1

ITEM	TEST	TEST PROCEDURE	CONDITION	REQUIREMENT	ACTUAL
1	Temperature Rise (via current cycling)	Measure the temperature rise at the rated current after 96 hours. (45 minutes ON and 15 minutes OFF). Fixture as required.	Mated	Temperature Rise: +30°C maximum	0.3 A min. with < 30°C Temperature Rise

6.7 MECHANICAL TEST GROUP 2

ITEM	TEST	TEST PROCEDURE	CONDITION	REQUIREMENT	ACTUAL
1	Connector Mate Forces (Module only)	Mate connector at a rate of 25 mm per min.	Mate	2.5 N / contact pair MAX insertion force	0.5-0.75 N / force
2	Connector Un-mate Forces (Module only)	Un-mate connector at a rate of 25 mm per min.	Un-mate	0.5 N / contact pair MAX withdrawal force	0.25-0.35 N / contact pair
3	Plug Mate Forces	Mate connector at a rate of 25 mm per min.	Mate	2.5 N / contact pair plus 50 N MAX	62 N – 82 N
4	De-Latch Plug (Axial Load)	Mate connector and place axial load on latch pull to de-latch plug	Un-mate	0.5 N / contact pair plus 20 N MAX	18 N – 24 N
5	Latch Pull (Axial Load)	Place axial load on plug pull with 6.35 mm diameter pin	Mate	25 N MIN	No physical damage

REVISION: D	ECR/ECN INFORMATION: EC No: UCP2012-2334 DATE: 2012 / 01 / 25	TITLE: PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	SHEET No. 11 of 17
DOCUMENT NUMBER: PS-76870-001	CREATED / REVISED BY: S. BOGIEL/JGONZALEZ	CHECKED BY: HAVERY	APPROVED BY: M. BANAKIS



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

6.8 MECHANICAL TEST GROUP 3

ITEM	TEST	TEST PROCEDURE	CONDITION	REQUIREMENT	ACTUAL
1	Terminal Retention Force	Axial pullout force on the terminal in the housing at a rate of 25 mm (1 in) per min.		4.5 N MINIMUM retention force	6.2 N MINIMUM
2	Normal Force	Apply a perpendicular force.		0.49 N, (50 grams) MINIMUM normal force	0.49 N, (50 grams) MINIMUM normal force

6.9 MECHANICAL TEST GROUP 4

ITEM	TEST	TEST PROCEDURE	CONDITION	REQUIREMENT	ACTUAL
1	Latitudinal Load	Mate connector and load plug with latitudinal load until open circuit. See section 9.	Mated	75 N MIN	90 N (no open circuit)
2	Longitudinal Load	Mate connector and load plug with longitudinal load until open circuit. See section 9.	Mated	75 N MIN	90 N (no open circuit)
3	Cable Pullout Force (Axial Load)	Mate plug to connector and apply an axial pullout force on the wire at a rate of 25 mm per min.	Mated	100 N MIN	133 N – 142 N
4	Cable Pullout Force (Right Angle Load)	Mate plug to connector and apply an right angle pullout force on the wire at a rate of 25 mm per min.	Mated	75 N MIN	125 N – 145 N

<u>REVISION:</u> D	<u>ECR/ECN INFORMATION:</u> EC No: UCP2012-2334 DATE: 2012 / 01 / 25	<u>TITLE:</u> PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	<u>SHEET No.</u> 12 of 17
<u>DOCUMENT NUMBER:</u> PS-76870-001	<u>CREATED / REVISED BY:</u> S. BOGIEL/JGONZALEZ	<u>CHECKED BY:</u> HAVERY	<u>APPROVED BY:</u> M. BANAKIS



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

6.10 MECHANICAL TEST GROUP 5

ITEM	TEST	TEST PROCEDURE	CONDITION	REQUIREMENT	ACTUAL
1	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	baseline	N/A
2	Wire Flex	Flex cable 180° for 20 cycles. Test per EIA 364-41 test cond. I: 24 AWG – with X = 40 mm 26 AWG – with X = 30 mm 28 AWG – with X = 30 mm	Mated	10 mΩ MAX (change from initial) No physical damage	20 cycles, no physical damage
3	Low Level Contact Resistance	EIA-364-23; apply a maximum voltage of 20 mV and a current of 100 mA.	Mated	<10 mΩ Δ max	<10 mΩ Δ max

6.11 MECHANICAL TEST GROUP 6

ITEM	TEST	TEST PROCEDURE	CONDITION	REQUIREMENT	ACTUAL
1	Compliant Pin Insertion into PCB	Apply an axial insertion force on the terminal at a rate of 25± 6 mm/min.		35 N (7.9 LBF) MAX.	1330 N MAX.
2	Compliant Pin Extraction into PCB	Apply an axial extraction force on the terminal at a rate of 25± 6 mm/min		9 N (2 lbf) MAX. retention force per pin	342 N MIN.

REVISION: D	ECR/ECN INFORMATION: EC No: UCP2012-2334 DATE: 2012 / 01 / 25	TITLE: PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	SHEET No. 13 of 17
DOCUMENT NUMBER: PS-76870-001	CREATED / REVISED BY: S. BOGIEL/JGONZALEZ	CHECKED BY: HAVERY	APPROVED BY: M. BANAKIS



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

7.0 PACKAGING

8.1 CONNECTOR

8.1.1 Product shall be packaged in Trays with Lids placed in Cartons, per the packaging specification as called out on the applicable assembly print.

8.1.2 Packaging shall meet the requirements of and be tested per the packaging specification as called out on the applicable assembly print.

8.2 PLUG AND CABLE ASSEMBLY

8.2.1 Product shall be packaged to protect against damage during handling, transit and storage.

<u>REVISION:</u> D	<u>ECR/ECN INFORMATION:</u> EC No: UCP2012-2334 DATE: 2012 / 01 / 25	<u>TITLE:</u> PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	<u>SHEET No.</u> 14 of 17
<u>DOCUMENT NUMBER:</u> PS-76870-001	<u>CREATED / REVISED BY:</u> S. BOGIEL/JGONZALEZ	<u>CHECKED BY:</u> HAVERY	<u>APPROVED BY:</u> M. BANAKIS

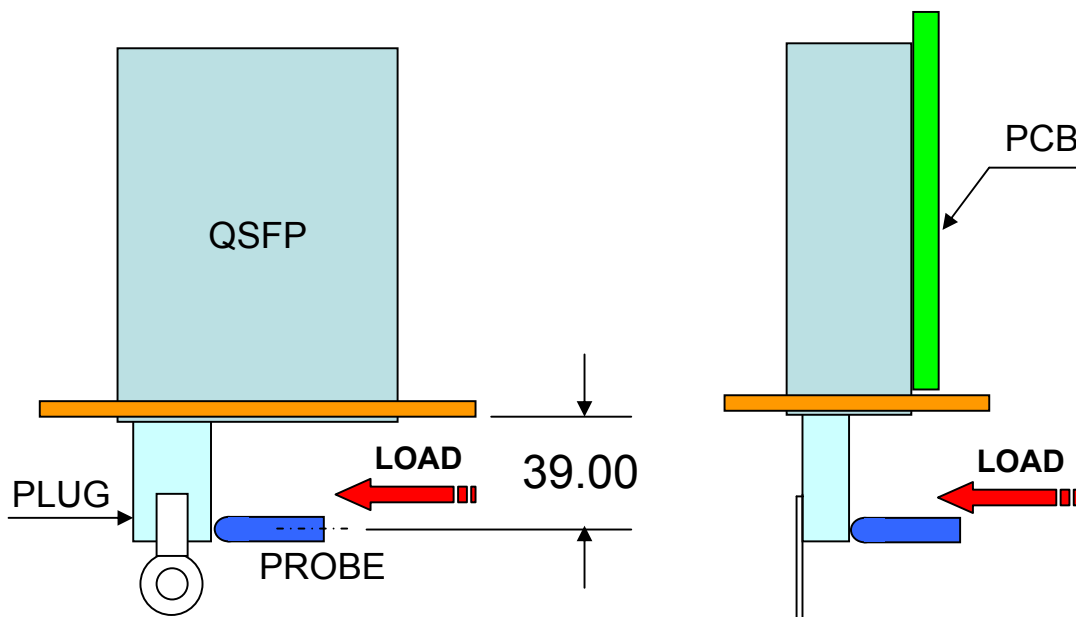


PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

8.0 GAGES AND FIXTURES

Test setup for latitudinal and longitudinal load testing and shell retention testing. Probe is about 6mm in diameter with a full radius nose. The probe is to be placed 20mm from the front edge of the receptacle and located at the centerline of the plug. Apply load to plug at a rate of 25mm per minute.

Test setup for peel and shear testing. Apply load to plug at a rate of 25mm per minute.



REVISION: D	ECR/ECN INFORMATION: EC No: UCP2012-2334 DATE: 2012 / 01 / 25	TITLE: PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	SHEET No. 15 of 17
DOCUMENT NUMBER: PS-76870-001	CREATED / REVISED BY: S. BOGIEL/JGONZALEZ	CHECKED BY: HAVERY	APPROVED BY: M. BANAKIS



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS

9.0 OTHER INFORMATION

10.1 INVERTED SMT APPLICATION

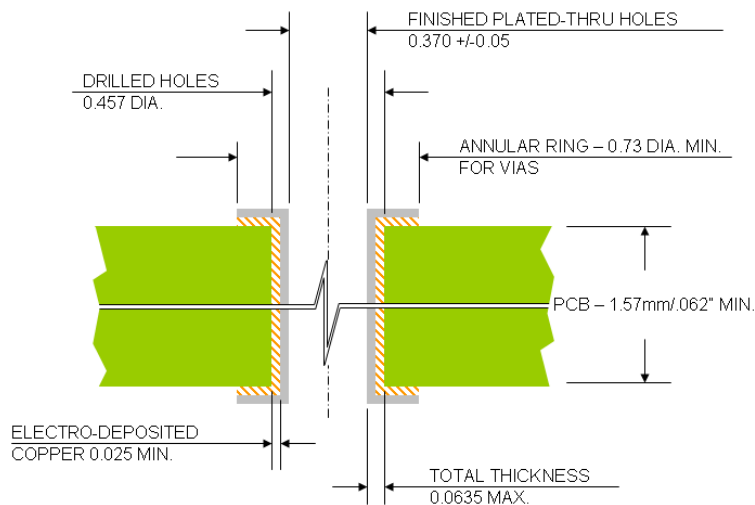
See AS-75586-001 Application Specification for inverted SMT application.

10.2 PCB REQUIREMENTS

The compliant pin shall be capable of being inserted one time.

The PCB hole shall be capable of retaining the compliant pin for a maximum of three insertions. The removal of the compliant pin from the PCB shall not damage the PCB hole beyond the point to be able to retain a compliant pin (that has not been inserted into a PCB).

0.370 mm Compliant Pin Drilled Hole Size: 0.457 mm (# 77 Drill)
 1.050 mm Cage Tail Drilled Hole Size: 1.092 mm (# 57 Drill)

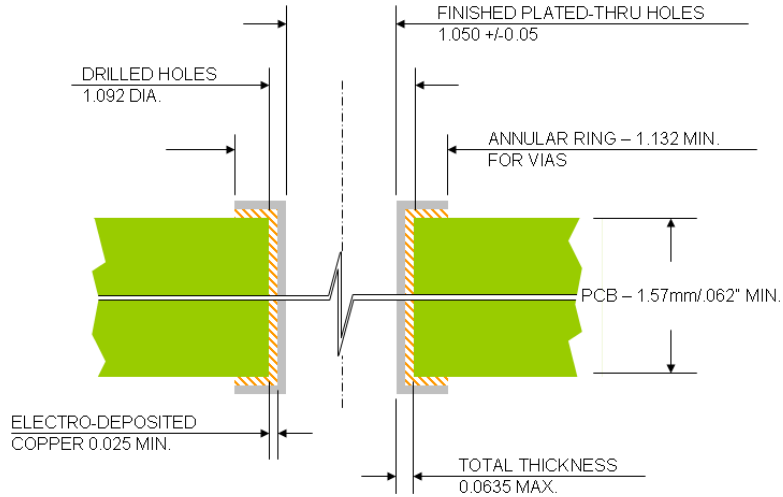


COMPLIANT PIN-HOLE DETAIL

REVISION: D	ECR/ECN INFORMATION: EC No: UCP2012-2334 DATE: 2012 / 01 / 25	TITLE: PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS		SHEET No. 16 of 17
DOCUMENT NUMBER: PS-76870-001	CREATED / REVISED BY: S. BOGIEL/JGONZALEZ	CHECKED BY: HAVERY	APPROVED BY: M. BANAKIS	



PRODUCT SPECIFICATION QSFP+ STACKED CONNECTORS



CAGE TAIL HOLE DETAIL

Note:

Depending upon the plating finish and plating process, a larger drill diameter may be used to achieve the finished hole specification.

<u>REVISION:</u> D	<u>ECR/ECN INFORMATION:</u> EC No: UCP2012-2334 DATE: 2012 / 01 / 25	<u>TITLE:</u> PRODUCT SPECIFICATION STACKED QSFP+ CONNECTORS	<u>SHEET No.</u> 17 of 17
<u>DOCUMENT NUMBER:</u> PS-76870-001	<u>CREATED / REVISED BY:</u> S. BOGIEL/JGONZALEZ	<u>CHECKED BY:</u> HAVERY	<u>APPROVED BY:</u> M. BANAKIS